

PCB P/N 878284-E

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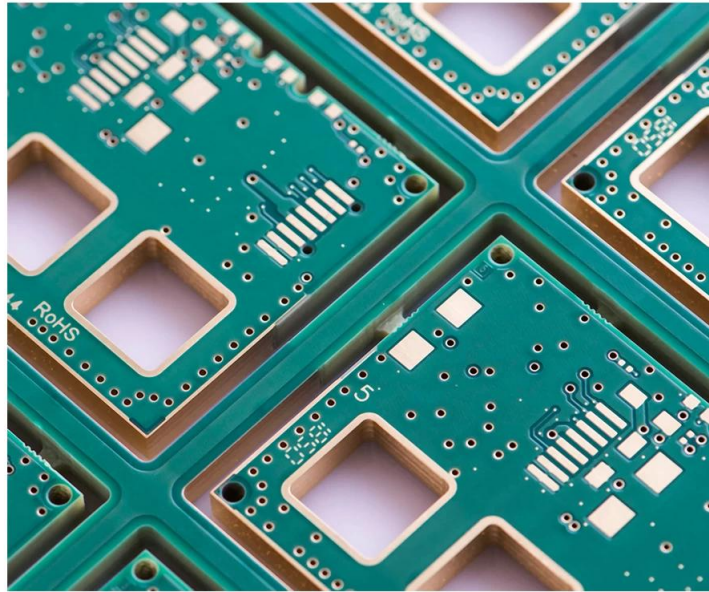
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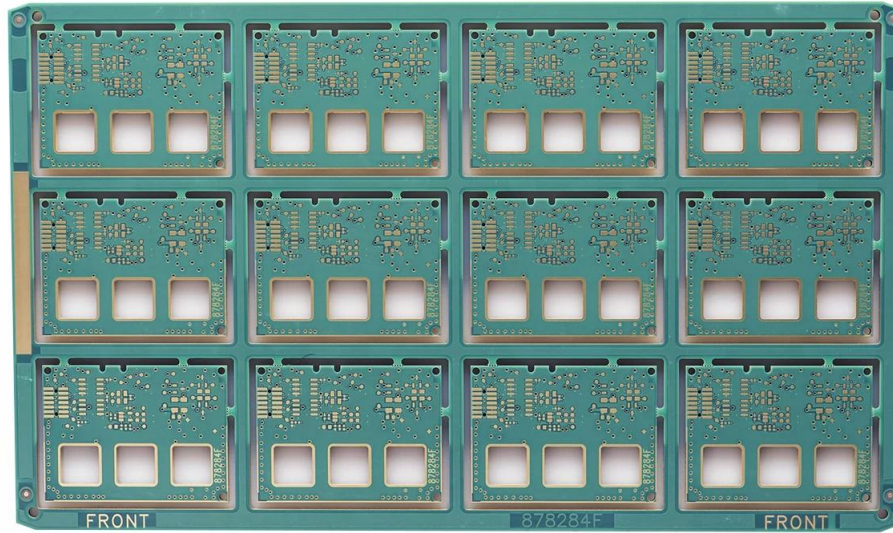
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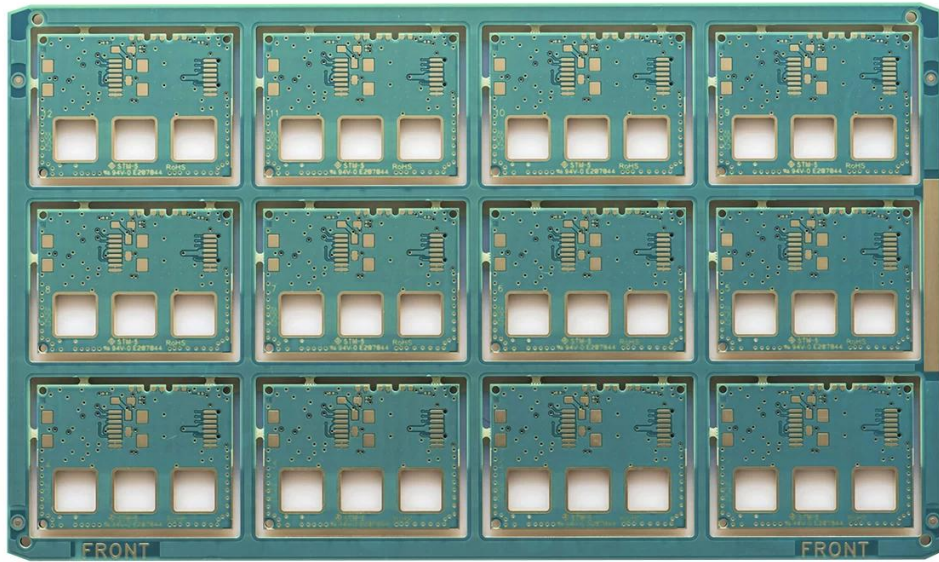
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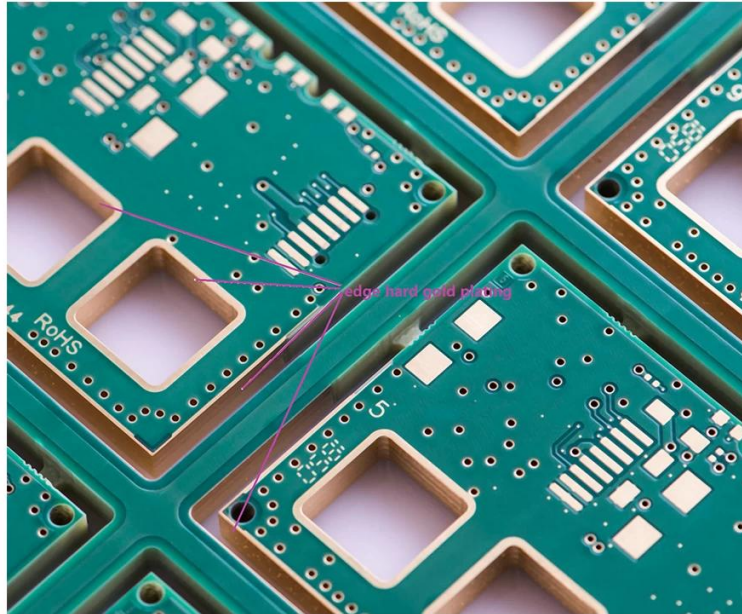
PCB P/N 878284-E

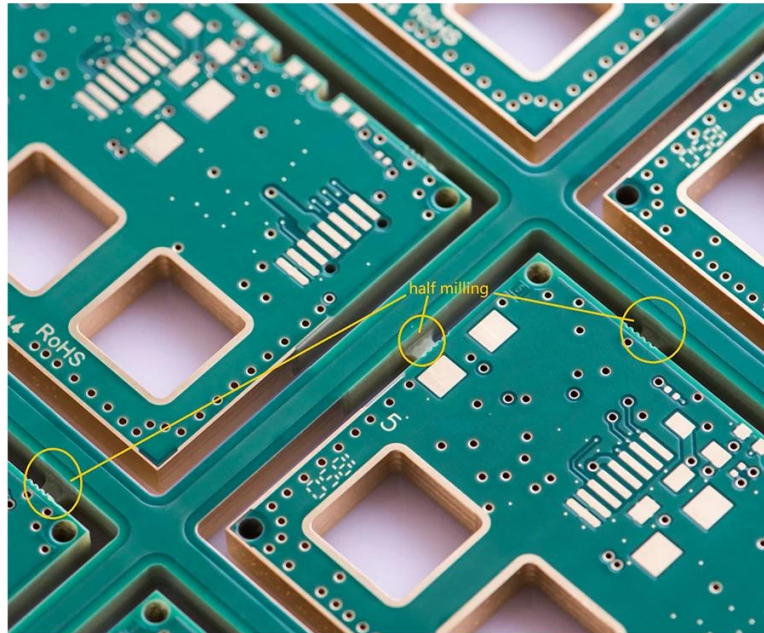
PCB P / N	878284-E
PCB Type	6L HDI
Material	FR-4 TG180
Thickness thk	3.80mm
Core Thickness	1/1 / 1/1/1 / 1OZ
Prepreg Thickness	0.1MM
Copper Weight (pc)	725
Copper Thickness / Copper	8 / 8mil
Surface Finish Y / N (Y/N)	N
Surface Finish: ENIG Au	0.075-0.125UM
Panel Size / Panel Size	244mm / 145mm
Panel Size	Dim X (mm): 51 □ Dim Y (mm): 37.7
Panelisation	Dim X (mm): 244 □ Dim Y (mm): 145 □ No of UPS: 12
Number of Units	N
Manufacturing Process	CNC











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QUALITY MANAGEMENT SYSTEM CERTIFICATE
Certificate No.: 16118Q10347R05

We hereby certify that
O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED
Credit No.: 61691591-000-07-17-2
Registration Add: ROOM 603D 6/F HANG PONT COMMERCIAL BUILDING, 31 TONKIN ST. CHEUNG SHA WAN, K.L. HK
Business Add: 1313 Floor 13 Fortune Building, Danshui Town Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System**
Which fulfills the requirements of the following standards
GB/T19001-2016 idt ISO9001:2015

Scope of certification
Sales of printed circuit boards

Initial Issuance period: February 27, 2018
This certificate is valid during: February 27, 2018 -- February 26, 2021
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Qualified mark	Second supervision and audit	Qualified mark
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The certification registration scope shall include those production services scope which fall to be covered by the relevant effective administrative permission and qualification permission required by the state. The effectiveness of this certificate shall be evaluated by annual surveillance audit of CICC. The certificate shall be valid when used together with the surveillance audit conclusion. The related information of this certification can be searched at the public website of website www.cicc.com.cn.

CICC IAF CNAS

201726 201VQZL430354 - Wiring, Printed - Component

UL ONLINE CERTIFICATIONS DIRECTORY

ZPMV2.E490354
Wiring, Printed - Component

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Wiring, Printed - Component

See General Information for Wiring, Printed - Components

O-LEADING SUPPLY CHAIN CO LIMITED 4190354
Fortune Building, Nanheng West Road
Room 1313
Huizhou, Guangdong 516211, CHINA

Type	Cond Width			SS/ DS/ Di	Area Diam	Solder		Temp		Flame	RoHS	C
	Min	Max	Min			Max	Class	DSR				
Hub/Bayer (mass laminate) printed wiring boards.												
O-LEADING-401												
	0.2 (0.004)	0.3 (0.012)	34 (1.34)	D6	12.7 (0.5)	260	10	130	V-0	-	-	-
O-LEADING-407												
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	D5	9.2 (0.4)	260	10	170	V-0	NI	-	-
Hub/Bayer printed wiring boards.												
O-LEADING-408												
	0.125 (0.005)	0.125 (0.005)	12 (0.47) min:1.25	D6	50.8 (2.0)	260	20	130	V-0	NI	-	-
Single layer printed wiring boards.												
O-LEADING-002												
	0.76 (0.015)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	105	V-0	NI	-	-
O-LEADING-003												
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	130	V-0	▲	-	-
O-LEADING-033												
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	S5	25.4 (1.0)	260	10	120	V-0	NI	-	-
O-LEADING-205												
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	D6	69.6 (2.7)	260	10	130	V-0	NI	-	-
O-LEADING-206												
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	D5	69.6 (2.7)	260	10	130	V-0	NI	-	-

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.
Last updated on 2017-01-27

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[http://www.ul.com/onlinecert/qci/qci.html?cert=ZPMV2.E490354&product=Wiring,Printed-Component&id=19](#)



Test Report No. CAVEC1805164701 Date: 03 Apr 2018 Page 2 of 8

Test Results:

Test Part Description:

Specimen No. SH1
SGS Sample ID CAN18-051647.001
Description Green "PCB"

Remarks:

- (1) 1 mg/kg = 1 ppm = 0.0001%
- (2) MDL = Method Detection Limit
- (3) ND = Not Detected (< MDL)
- (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method: With reference to IEC 62321-4:2014+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Det
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



SGS shall not be held responsible for any errors or omissions in this report. The client is responsible for the accuracy of the data provided. The client is also responsible for the accuracy of the data provided. The client is also responsible for the accuracy of the data provided. The client is also responsible for the accuracy of the data provided.

Member of the SGS Group (SGL SA)

3. what are the different types of PCB materials?

FR4 is the most common PCB material. Other materials include TG, Arlon, Teflon, PI, etc.

4. What are the different types of PCB manufacturing processes?

Gerber 274-X, Cam350, CAD, Protel 99se, PADS, DXP, Eagle.

5. What are the different types of PCB assembly processes?

Hand assembly, SMT, AOI, PTH, E/T, etc.